SPECTRA7

Spectra7 Partners with Wandtec on 100, 200 and 400Gbps Data Center Interconnects using 56Gbps PAM4 GaugeChanger™ ICs

Innovative Supplier Sees Strong Opportunities for Spectra7 Enabled Active Copper Cables for Lengths Up to 10 Meters

SAN JOSE, Calif., April 19, 2021 /CNW/ -- (TSXV:SEV) Spectra7 Microsystems Inc. ("**Spectra7**" or the "**Company**"), a leading provider of high-performance analog semiconductor products for broadband connectivity markets, and Wandtec, an innovative technology leading interconnect supplier, today announced they are collaborating on Spectra7 enabled 100G DSFP, 200G QSFP56 and 400G QSFP-DD Active Copper Cable (ACC) interconnects targeted at major datacenter operators and high-performance computing OEMs.

"Spectra7 has created a compelling solution to address the dramatically increasing power and cost of data center interconnects," said Xin Wu, CEO at Wandtec. "We are seeing significant interest from our customers for ACCs with Spectra7 technology and are pleased to be partnered to deliver unprecedented solutions for low power, low latency and extended reach. In combination with our innovative WDTCDR™ Twinax cable and patent pending crosstalk noise mitigation technology, we are able to extend 56G PAM4 based copper interconnects to lengths of 10m while being compliant to the IEEE 802.3cd standard."

The initial collaboration is for 100Gbps DSFP interconnects. Major China operators including Alibaba, Baidu and Tencent are choosing this standard for higher speed and higher density switch and server connections. The DSFP standard using 56G PAM4 signaling enables a 4x increase in bandwidth over currently deployed SFP28 interconnects but the higher data rate limits the interconnect length that can be served by low-cost direct-attach copper (DAC) passive cables. Spectra7's GaugeChanger™ silicon enables ACC cables up to three times the reach of passive DSFP copper cables.

"Wandtec is an up-and-coming innovative technology leader in data center interconnects," said Spectra7 CEO Raouf Halim. "Partnering with them is significant and will accelerate adoption of our technology in this rapidly growing market."

About Wandtec

Wandtec is a spin-off of 30+ years old wire-harness manufacturer dedicated for high-speed copper, hybrid copper and optical, and high-speed interconnect module technology innovation and manufacturing services. Our innovation in software-defined engineering & manufacturing enables the finest processing techniques of copper cable interconnects at um scale, which minimizes the discontinuity where the three-dimensional transitions of the combination of PCB, Twinax (Micro-coax), Connectors, Optical-engine, and/or fiber playing critical roles in the performance. In-line simulation and modeling, 100% testing and data-tracking, artificial intelligence, and automation set our foundation of product performance and reliability excellence.

With the operations in both USA and China, Wandtec's 123210 operation principle shortens customers' time-to-market 30%~50%.

For more information, please visit https://www.wandtec.com/.

ABOUT SPECTRA7 MICROSYSTEMS INC.

Spectra7 Microsystems Inc. is a high-performance analog semiconductor company delivering unprecedented bandwidth, speed and resolution to enable disruptive industrial design for leading electronics manufacturers in virtual reality, augmented reality, mixed reality, data centers and other connectivity markets. Spectra7 is based in San Jose, California with a design center in Cork, Ireland and technical support location in Dongguan, China. For more information, please visit www.spectra7.com.

Neither the TSX Venture Exchange nor its regulation services provided (as that term is defined in the policies of the TSX Venture Exchange) accepts responsibility for the adequacy or accuracy of this release.

CAUTIONARY NOTES

Certain statements contained in this press release constitute "forward-looking statements". All statements other than statements of historical fact contained in this press release, including, without limitation, those regarding the Company's strategy, plans, objectives, goals and targets, and any statements preceded by, followed by or that include the words "believe", "expect", "aim", "intend", "plan", "continue", "will", "may", "would", "anticipate", "estimate", "forecast", "predict", "project", "seek", "should" or similar expressions or the negative thereof, are forward-looking statements. These statements are not historical facts but instead represent only the Company's expectations, estimates and projections regarding future events. These statements are not guarantees of future performance and involve assumptions, risks and uncertainties that are difficult to predict. Therefore, actual results may differ materially from what is expressed, implied or forecasted in such forward-looking statements. Additional factors that could cause actual results, performance or achievements to differ materially include, but are not limited to the risk factors discussed in the Company's Annual Information Form for the year ended December 31, 2019. Management provides forward-looking statements because it believes they provide useful information to investors when considering their investment objectives and cautions investors not to place undue reliance on forward-looking information. Consequently, all of the forward-looking statements made in this press release are qualified by these cautionary statements and other cautionary statements or factors contained herein, and there can be no assurance that the actual results or developments will be realized or, even if substantially realized, that they will have the expected consequences to, or effects on, the Company. These forward-looking statements are made as of the date of this press release and the Company assumes no obligation to update or revise them to reflect subsequent information, events or circumstances or otherwise, except as required by law.

For more information, please contact:

Spectra7 Microsystems Inc.
Justin Leighton
Investor Relations
647-578-7996
ir@spectra7.com

Spectra7 Microsystems Inc.
David Mier
Chief Financial Officer
925-858-7011
pr@spectra7.com

View original content to download multimedia:
http://www.prnewswire.com/news-releases/spectra7-partners-with-wandtec-on-100-200-and-400gbps-data-center-interconnects-using-56gbps-pam4-gaugechange

SOURCE Spectra7 Microsystems Inc.

View original content to download multimedia: http://www.newswire.ca/en/releases/archive/April2021/19/c3395.html

%SEDAR: 00031105E

CO: Spectra7 Microsystems Inc.

CNW 08:55e 19-APR-21